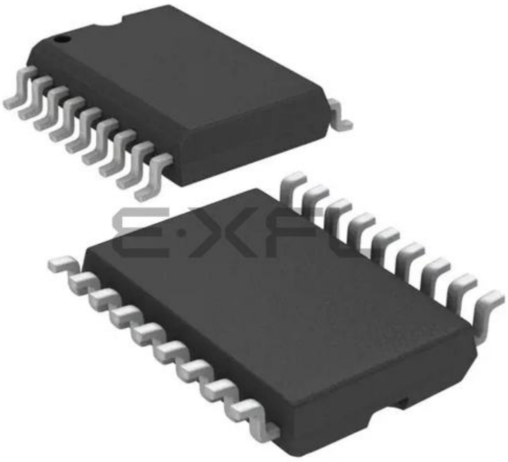

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	20 MIPS
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	12
Program Memory Size	12KB (4K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic30f2011t-20i-so

TABLE 5-5: FOSC CONFIGURATION BITS DESCRIPTION FOR dsPIC30F4011/4012 AND dsPIC30F5011/5013

Bit Field	Register	Description
FCKSM<1:0>	FOSC	**Clock Switching Mode** 1x = Clock switching is disabled, Fail-Safe Clock Monitor is disabled 01 = Clock switching is enabled, Fail-Safe Clock Monitor is disabled 00 = Clock switching is enabled, Fail-Safe Clock Monitor is enabled
FOS<1:0>	FOSC	**Oscillator Source Selection on POR** 11 = Primary Oscillator 10 = Internal Low-Power RC Oscillator 01 = Internal Fast RC Oscillator 00 = Low-Power 32 kHz Oscillator (Timer1 Oscillator)
FPR<3:0>	FOSC	**Primary Oscillator Mode** 1111 = ECIO w/PLL 16X – External Clock mode with 16X PLL. OSC2 pin is I/O 1110 = ECIO w/PLL 8X – External Clock mode with 8X PLL. OSC2 pin is I/O 1101 = ECIO w/PLL 4X – External Clock mode with 4X PLL. OSC2 pin is I/O 1100 = ECIO – External Clock mode. OSC2 pin is I/O 1011 = EC – External Clock mode. OSC2 pin is system clock output (FOSC/4) 1010 = FRC w/PLL 8x – Internal fast RC oscillator with 8x PLL. OSC2 pin is I/O 1001 = ERC – External RC Oscillator mode. OSC2 pin is system clock output (FOSC/4) 1000 = ERCIO – External RC Oscillator mode. OSC2 pin is I/O 0111 = XT w/PLL 16X – XT Crystal Oscillator mode with 16X PLL 0110 = XT w/PLL 8X – XT Crystal Oscillator mode with 8X PLL 0101 = XT w/PLL 4X – XT Crystal Oscillator mode with 4X PLL 0100 = XT – XT Crystal Oscillator mode (4 MHz-10 MHz crystal) 0011 = FRC w/PLL 16x – Internal fast RC oscillator with 16x PLL. OSC2 pin is I/O 0010 = HS – HS Crystal Oscillator mode (10 MHz-25 MHz crystal) 0001 = FRC w/PLL 4x – Internal fast RC oscillator with 4x PLL. OSC2 pin is I/O 0000 = XTL – XTL Crystal Oscillator mode (200 kHz-4 MHz crystal)

TABLE 5-6: FOSC CONFIGURATION BITS DESCRIPTION FOR dsPIC30F2011/2012, dsPIC30F3010/3011/3012/3013/3014, dsPIC30F4013, dsPIC30F5015/5016, dsPIC30F6010A/6011A/6012A/6013A/6014A AND dsPIC30F6015 (CONTINUED)

Bit Field	Register	Description
FPR<4:0>	FOSC	**Alternate Oscillator Mode (when FOS<2:0> = `011b`)** `1xxxx` = Reserved (do not use) `0111x` = Reserved (do not use) `01101` = Reserved (do not use) `01100` = ECIO – External clock. OSC2 pin is I/O `01011` = EC – External clock. OSC2 pin is system clock output (FOSC/4) `01010` = Reserved (do not use) `01001` = ERC – External RC oscillator. OSC2 pin is system clock output (FOSC/4) `01000` = ERCIO – External RC oscillator. OSC2 pin is I/O `00111` = Reserved (do not use) `00110` = Reserved (do not use) `00101` = Reserved (do not use) `00100` = XT – XT crystal oscillator (4 MHz-10 MHz crystal) `00010` = HS – HS crystal oscillator (10 MHz-25 MHz crystal) `00001` = Reserved (do not use) `00000` = XTL – XTL crystal oscillator (200 kHz-4 MHz crystal)

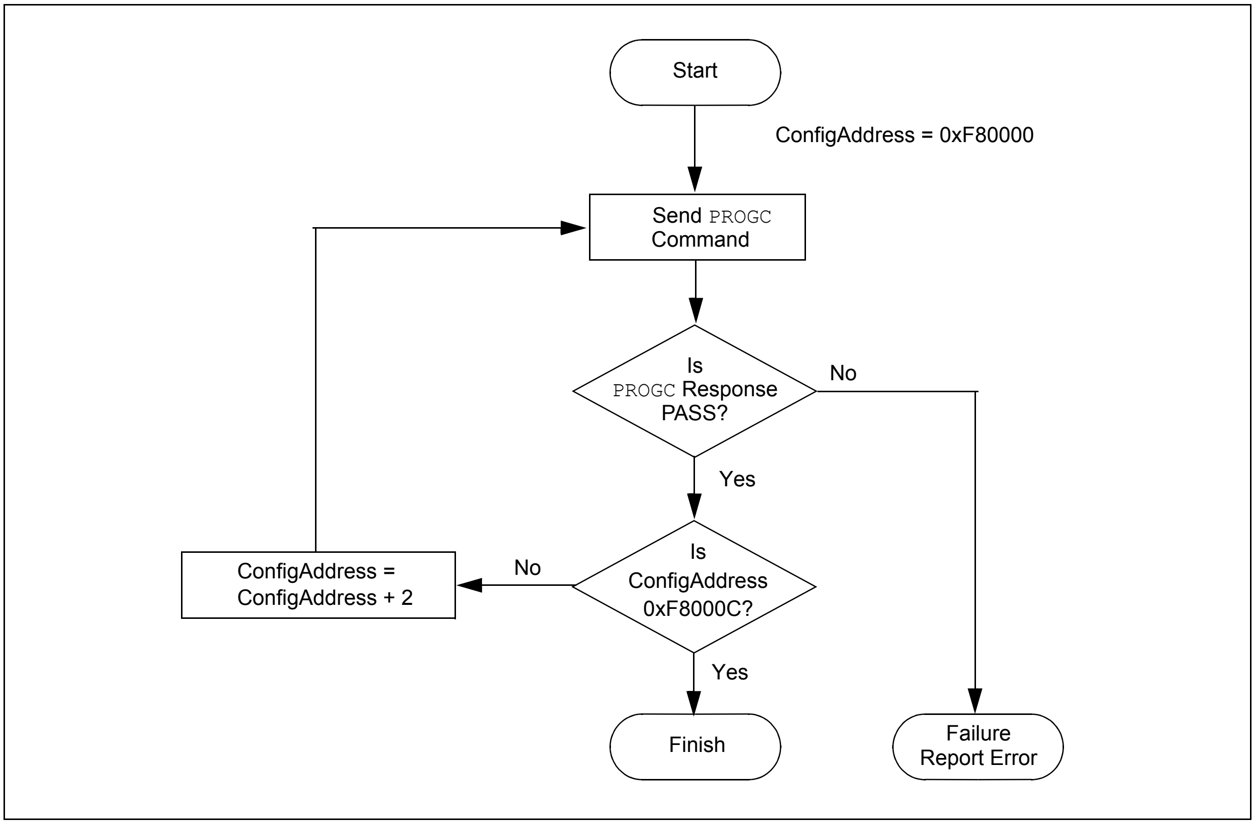
TABLE 5-7: CONFIGURATION BITS DESCRIPTION

Bit Field	Register	Description
FWPSA<1:0>	FWDT	**Watchdog Timer Prescaler A** `11` = 1:512 `10` = 1:64 `01` = 1:8 `00` = 1:1
FWPSB<3:0>	FWDT	**Watchdog Timer Prescaler B** `1111` = 1:16 `1110` = 1:15 • • • `0001` = 1:2 `0000` = 1:1
FWDTEN	FWDT	**Watchdog Enable** `1` = Watchdog enabled (LPRC oscillator cannot be disabled. Clearing the SWDTEN bit in the RCON register will have no effect) `0` = Watchdog disabled (LPRC oscillator can be disabled by clearing the SWDTEN bit in the RCON register)
MCLREN	FBORPOR	**Master Clear Enable** `1` = Master Clear pin ($\overline{\text{MCLR}}$) is enabled `0` = $\overline{\text{MCLR}}$ pin is disabled
PWMPIN	FBORPOR	**Motor Control PWM Module Pin Mode** `1` = PWM module pins controlled by PORT register at device Reset (tri-stated) `0` = PWM module pins controlled by PWM module at device Reset (configured as output pins)
HPOL	FBORPOR	**Motor Control PWM Module High-Side Polarity** `1` = PWM module high-side output pins have active-high output polarity `0` = PWM module high-side output pins have active-low output polarity
LPOL	FBORPOR	**Motor Control PWM Module Low-Side Polarity** `1` = PWM module low-side output pins have active-high output polarity `0` = PWM module low-side output pins have active-low output polarity
BOREN	FBORPOR	**PBOR Enable** `1` = PBOR enabled `0` = PBOR disabled
BORV<1:0>	FBORPOR	**Brown-out Voltage Select** `11` = 2.0V (not a valid operating selection) `10` = 2.7V `01` = 4.2V `00` = 4.5V
FPWRT<1:0>	FBORPOR	**Power-on Reset Timer Value Select** `11` = PWRT = 64 ms `10` = PWRT = 16 ms `01` = PWRT = 4 ms `00` = Power-up Timer disabled
RBS<1:0>	FBS	**Boot Segment Data RAM Code Protection (only present in dsPIC30F5011/5013/6010A/6011A/6012A/6013A/6014A/6015)** `11` = No Data RAM is reserved for Boot Segment `10` = Small-sized Boot RAM [128 bytes of RAM are reserved for Boot Segment] `01` = Medium-sized Boot RAM [256 bytes of RAM are reserved for Boot Segment] `00` = Large-sized Boot RAM [512 bytes of RAM are reserved for Boot Segment in dsPIC30F5011/5013, and 1024 bytes in dsPIC30F6010A/6011A/6012A/6013A/6014A/6015]

5.8 Exiting Enhanced ICSP Mode

The Enhanced ICSP mode is exited by removing power from the device or bringing $\overline{\text{MCLR}}$ to V_{IL}. When normal user mode is next entered, the program that was stored using Enhanced ICSP will execute.

FIGURE 5-5: CONFIGURATION BIT PROGRAMMING FLOW



6.6 Configuration Information in the Hexadecimal File

To allow portability of code, the programmer must read the Configuration register locations from the hexadecimal file. If configuration information is not present in the hexadecimal file, a simple warning message should be issued by the programmer. Similarly, while saving a hexadecimal file, all configuration information must be included. An option to not include the configuration information can be provided.

Microchip Technology Inc. feels strongly that this feature is important for the benefit of the end customer.

6.7 Unit ID

The dsPIC30F devices contain 32 instructions of Unit ID. These are located at addresses 0x8005C0 through 0x8005FF. The Unit ID can be used for storing product information such as serial numbers, system manufacturing dates, manufacturing lot numbers and other such application-specific information.

A Bulk Erase does not erase the Unit ID locations. Instead, erase all executive memory using steps 1-4 as shown in Table 12-1, and program the Unit ID along with the programming executive. Alternately, use a Row Erase to erase the row containing the Unit ID locations.

6.8 Checksum Computation

Checksums for the dsPIC30F are 16 bits in size. The checksum is to total sum of the following:

- Contents of code memory locations
- Contents of Configuration registers

Table A-1 describes how to calculate the checksum for each device. All memory locations are summed one byte at a time, using only their native data size. More specifically, Configuration and device ID registers are summed by adding the lower two bytes of these locations (the upper byte is ignored), while code memory is summed by adding all three bytes of code memory.

Note: The checksum calculation differs depending on the code-protect setting. Table A-1 describes how to compute the checksum for an unprotected device and a read-protected device. Regardless of the code-protect setting, the Configuration registers can always be read.

7.0 PROGRAMMER – PROGRAMMING EXECUTIVE COMMUNICATION

7.1 Communication Overview

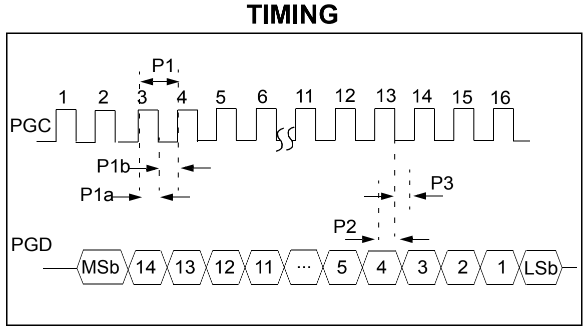
The programmer and programming executive have a master-slave relationship, where the programmer is the master programming device and the programming executive is the slave.

All communication is initiated by the programmer in the form of a command. Only one command at a time can be sent to the programming executive. In turn, the programming executive only sends one response to the programmer after receiving and processing a command. The programming executive command set is described in **Section 8.0 "Programming Executive Commands"**. The response set is described in **Section 9.0 "Programming Executive Responses"**.

7.2 Communication Interface and Protocol

The Enhanced ICSP interface is a 2-wire SPI interface implemented using the PGC and PGD pins. The PGC pin is used as a clock input pin, and the clock source must be provided by the programmer. The PGD pin is used for sending command data to, and receiving response data from, the programming executive. All serial data is transmitted on the falling edge of PGC and latched on the rising edge of PGC. All data transmissions are sent Most Significant bit (MSb) first, using 16-bit mode (see Figure 7-1).

FIGURE 7-1: PROGRAMMING EXECUTIVE SERIAL TIMING



Since a 2-wire SPI interface is used, and data transmissions are bidirectional, a simple protocol is used to control the direction of PGD. When the programmer completes a command transmission, it releases the PGD line and allows the programming executive to drive this line high. The programming executive keeps the PGD line high to indicate that it is processing the command.

After the programming executive has processed the command, it brings PGD low for 15 µsec to indicate to the programmer that the response is available to be

8.5 Command Descriptions

All commands that are supported by the programming executive are described in **Section 8.5.1 "SCHECK Command"** through **Section 8.5.11 "QVER Command"**.

8.5.1 SCHECK COMMAND

15–12	11–0
Opcode	Length

Field	Description
Opcode	0x0
Length	0x1

The SCHECK command instructs the programming executive to do nothing, but generate a response. This command is used as a "sanity check" to verify that the programming executive is operational.

Expected Response (2 words):
0x1000
0x0002

Note:	This instruction is not required for programming, but is provided for development purposes only.

8.5.2 READD COMMAND

15–12	11–8	7–0
Opcode	Length	
Reserved0	N	
Reserved1		Addr_MSB
Addr_LS		

Field	Description
Opcode	0x1
Length	0x4
Reserved0	0x0
N	Number of 16-bit words to read (max of 2048)
Reserved1	0x0
Addr_MSB	MSB of 24-bit source address
Addr_LS	LS 16 bits of 24-bit source address

The READD command instructs the programming executive to read N 16-bit words of memory starting from the 24-bit address specified by Addr_MSB and Addr_LS. This command can only be used to read 16-bit data. It can be used to read data EEPROM, Configuration registers and the device ID.

Expected Response (2+N words):
0x1100
N + 2
Data word 1
...
Data word N

Note:	Reading unimplemented memory will cause the programming executive to reset.

8.5.3 READP COMMAND

15–12	11–8	7–0
Opcode	Length	
N		
Reserved		Addr_MSB
Addr_LS		

Field	Description
Opcode	0x2
Length	0x4
N	Number of 24-bit instructions to read (max of 32768)
Reserved	0x0
Addr_MSB	MSB of 24-bit source address
Addr_LS	LS 16 bits of 24-bit source address

The READP command instructs the programming executive to read N 24-bit words of code memory starting from the 24-bit address specified by Addr_MSB and Addr_LS. This command can only be used to read 24-bit data. All data returned in response to this command uses the packed data format described in **Section 8.3 "Packed Data Format"**.

Expected Response (2 + 3 * N/2 words for N even):
0x1200
2 + 3 * N/2
Least significant program memory word 1
...
Least significant data word N

Expected Response (4 + 3 * (N – 1)/2 words for N odd):
0x1200
4 + 3 * (N – 1)/2
Least significant program memory word 1
...
MSB of program memory word N (zero padded)

Note:	Reading unimplemented memory will cause the programming executive to reset.

8.5.4 PROGD COMMAND

15–12	11–8	7–0
Opcode	Length	
Reserved		Addr_MSB
Addr_LS		
D_1		
D_2		
...		
D_16		

Field	Description
Opcode	0x4
Length	0x13
Reserved	0x0
Addr_MSB	MSB of 24-bit destination address
Addr_LS	LS 16 bits of 24-bit destination address
D_1	16-bit data word 1
D_2	16-bit data word 2
...	16-bit data words 3 through 15
D_16	16-bit data word 16

The PROGD command instructs the programming executive to program one row of data EEPROM. The data to be programmed is specified by the 16 data words (D_1, D_2,..., D_16) and is programmed to the destination address specified by Addr_MSB and Addr_LSB. The destination address should be a multiple of 0x20.

Once the row of data EEPROM has been programmed, the programming executive verifies the programmed data against the data in the command.

Expected Response (2 words):
0x1400
0x0002

Note:	Refer to Table 5-3 for data EEPROM size information.

9.2.3 QE_Code FIELD

The QE_Code is a byte in the first word of the response. This byte is used to return data for query commands, and error codes for all other commands.

When the programming executive processes one of the two query commands (QBLANK or QVER), the returned opcode is always PASS and the QE_Code holds the query response data. The format of the QE_Code for both queries is shown in Table 9-3.

TABLE 9-3: QE_Code FOR QUERIES

Query	QE_Code
QBLANK	0x0F = Code memory and data EEPROM are NOT blank 0xF0 = Code memory and data EEPROM are blank
QVER	0xMN, where programming executive software version = M.N (i.e., 0x32 means software version 3.2)

When the programming executive processes any command other than a Query, the QE_Code represents an error code. Supported error codes are shown in Table 9-4. If a command is successfully processed, the returned QE_Code is set to 0x0, which indicates that there was no error in the command processing. If the verify of the programming for the PROGD, PROGP or PROGC command fails, the QE_Code is set to 0x1. For all other programming executive errors, the QE_Code is 0x2.

TABLE 9-4: QE_Code FOR NON-QUERY COMMANDS

QE_Code	Description
0x0	No error
0x1	Verify failed
0x2	Other error

9.2.4 RESPONSE LENGTH

The response length indicates the length of the programming executive's response in 16-bit words. This field includes the 2 words of the response header.

With the exception of the response for the READD and READP commands, the length of each response is only 2 words.

The response to the READD command is N + 2 words, where N is the number of words specified in the READD command.

The response to the READP command uses the packed instruction word format described in **Section 8.3 "Packed Data Format"**. When reading an odd number of program memory words (N odd), the response to the READP command is (3 • (N + 1)/2 + 2) words. When reading an even number of program memory words (N even), the response to the READP command is (3 • N/2 + 2) words.

11.0 ICSP™ MODE

11.1 ICSP Mode

ICSP mode is a special programming protocol that allows you to read and write to the dsPIC30F programming executive. The ICSP mode is the second (and slower) method used to program the device. This mode also has the ability to read the contents of executive memory to determine whether the programming executive is present. This capability is accomplished by applying control codes and instructions serially to the device using pins PGC and PGD.

In ICSP mode, the system clock is taken from the PGC pin, regardless of the device's oscillator Configuration bits. All instructions are first shifted serially into an internal buffer, then loaded into the Instruction register and executed. No program fetching occurs from internal memory. Instructions are fed in 24 bits at a time. PGD is used to shift data in and PGC is used as both the serial shift clock and the CPU execution clock.

Data is transmitted on the rising edge and latched on the falling edge of PGC. For all data transmissions, the Least Significant bit (LSb) is transmitted first.

> **Note 1:** During ICSP operation, the operating frequency of PGC must not exceed 5 MHz.
>
> **2:** Because ICSP is slower, it is recommended that only Enhanced ICSP (E-ICSP) mode be used for device programming, as described in **Section 5.1 "Overview of the Programming Process"**.

11.2 ICSP Operation

Upon entry into ICSP mode, the CPU is idle. Execution of the CPU is governed by an internal state machine. A 4-bit control code is clocked in using PGC and PGD, and this control code is used to command the CPU (see Table 11-1).

The SIX control code is used to send instructions to the CPU for execution, while the REGOUT control code is used to read data out of the device via the VISI register. The operation details of ICSP mode are provided in **Section 11.2.1 "SIX Serial Instruction Execution"** and **Section 11.2.2 "REGOUT Serial Instruction Execution"**.

TABLE 11-1: CPU CONTROL CODES IN ICSP™ MODE

4-bit Control Code	Mnemonic	Description
`0000b`	SIX	Shift in 24-bit instruction and execute.
`0001b`	REGOUT	Shift out the VISI register.
`0010b-1111b`	N/A	Reserved.

11.2.1 SIX SERIAL INSTRUCTION EXECUTION

The SIX control code allows execution of dsPIC30F assembly instructions. When the SIX code is received, the CPU is suspended for 24 clock cycles as the instruction is then clocked into the internal buffer. Once the instruction is shifted in, the state machine allows it to be executed over the next four clock cycles. While the received instruction is executed, the state machine simultaneously shifts in the next 4-bit command (see Figure 11-2).

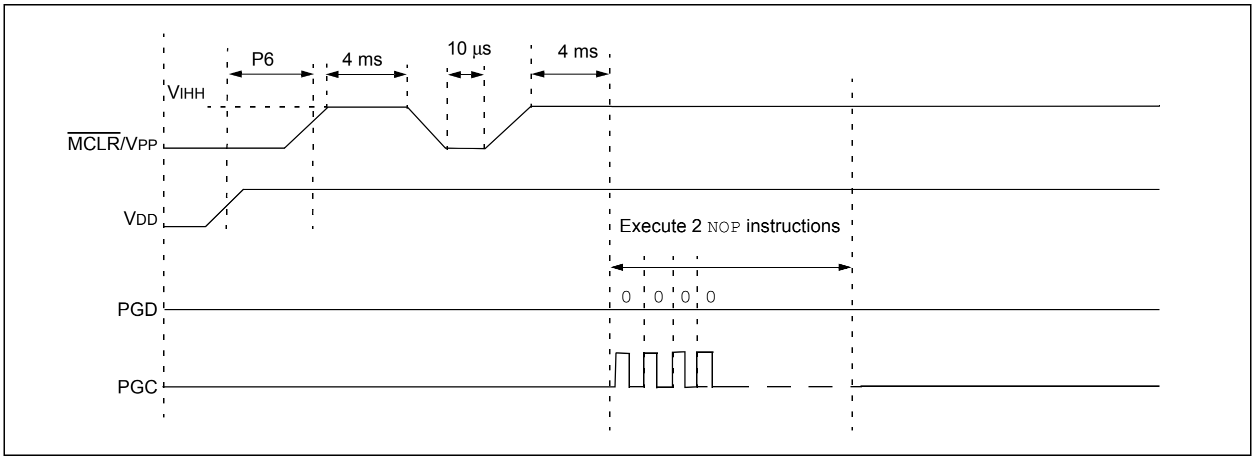
> **Note 1:** Coming out of the ICSP entry sequence, the first 4-bit control code is always forced to SIX and a forced NOP instruction is executed by the CPU. Five additional PGC clocks are needed on start-up, thereby resulting in a 9-bit SIX command instead of the normal 4-bit SIX command. After the forced SIX is clocked in, ICSP operation resumes as normal (the next 24 clock cycles load the first instruction word to the CPU). See Figure 11-1 for details.
>
> **2:** `TBLRDH`, `TBLRDL`, `TBLWTH` and `TBLWTL` instructions must be followed by a `NOP` instruction.

11.3 Entering ICSP Mode

The ICSP mode is entered by holding PGC and PGD low, raising $\overline{MCLR}$/VPP to VIHH (high voltage), and then performing additional steps as illustrated in Figure 11-4.

Note 1:	The sequence that places the device into ICSP mode places all unused I/O pins to the high-impedance state.
2:	Once ICSP mode is entered, the PC is set to 0x0 (the Reset vector).
3:	Before leaving the Reset vector, execute two `GOTO` instructions, followed by a single `NOP` instruction must be executed.

FIGURE 11-4: ENTERING ICSP™ MODE



11.6 Erasing Program Memory in Low-Voltage Systems

The procedure for erasing program memory (all code memory and data memory) in low-voltage systems (with VDD between 2.5 volts and 4.5 volts) is quite different than the procedure for erasing program memory in normal-voltage systems. Instead of using a Bulk Erase operation, each region of memory must be individually erased by row. Namely, all of the code memory, executive memory and data memory must be erased one row at a time. This procedure is detailed in Table 11-5.

Due to security restrictions, the FBS, FSS and FGS register cannot be erased in low-voltage systems. Once any bits in the FGS register are programmed to '0', they can only be set back to '1' by performing a Bulk Erase in a normal-voltage system. Alternatively, a Segment Erase operation can be performed instead of a Bulk Erase.

Normal-voltage systems can also be used to erase program memory as shown in Table 11-5. However, since this method is more time-consuming and does not clear the code-protect bits, it is not recommended.

Note:	Program memory must be erased before writing any data to program memory.

TABLE 11-5: SERIAL INSTRUCTION EXECUTION FOR ERASING PROGRAM MEMORY (EITHER IN LOW-VOLTAGE OR NORMAL-VOLTAGE SYSTEMS)

Command (Binary)	Data (Hexadecimal)	Description
Step 1: Exit the Reset vector.		
0000 0000 0000	040100 040100 000000	GOTO 0x100 GOTO 0x100 NOP
Step 2: Initialize NVMADR and NVMADRU to erase code memory and initialize W7 for row address updates.		

0000
0000
0000
0000
	EB0300
	883B16
	883B26
	200407
		CLR W6
		MOV W6, NVMADR
		MOV W6, NVMADRU
		MOV #0x40, W7

Step 3: Set NVMCON to erase 1 row of code memory.		
0000 0000	24071A 883B0A	MOV #0x4071, W10 MOV W10, NVMCON
Step 4: Unlock the NVMCON to erase 1 row of code memory.		

0000
0000
0000
0000
	200558
	883B38
	200AA9
	883B39
		MOV #0x55, W8
		MOV W8, NVMKEY
		MOV #0xAA, W9
		MOV W9, NVMKEY

Step 5: Initiate the erase cycle.		
0000 0000 0000 — 0000 0000 0000 0000 0000	A8E761 000000 000000 — 000000 000000 A9E761 000000 000000	BSET NVMCON, #WR NOP NOP Externally time 'P13a' ms (see **Section 13.0 "AC/DC Characteristics and Timing Requirements"**) NOP NOP BCLR NVMCON, #WR NOP NOP

TABLE 11-5: SERIAL INSTRUCTION EXECUTION FOR ERASING PROGRAM MEMORY (EITHER IN LOW-VOLTAGE OR NORMAL-VOLTAGE SYSTEMS) (CONTINUED)

Command (Binary)	Data (Hexadecimal)	Description
Step 6: Update the row address stored in NVMADRU:NVMADR. When W6 rolls over to 0x0, NVMADRU must be incremented.		

0000
0000
0000
0000
	430307
	AF0042
	EC2764
	883B16
		`ADD W6, W7, W6`
		`BTSC SR, #C`
		`INC NVMADRU`
		`MOV W6, NVMADR`

Step 7: Reset device internal PC.		
0000 0000	040100 000000	`GOTO 0x100` `NOP`
Step 8: Repeat Steps 3-7 until all rows of code memory are erased.		
Step 9: Initialize NVMADR and NVMADRU to erase executive memory and initialize W7 for row address updates.		

0000
0000
0000
0000
0000
	EB0300
	883B16
	200807
	883B27
	200407
		`CLR W6`
		`MOV W6, NVMADR`
		`MOV #0x80, W7`
		`MOV W7, NVMADRU`
		`MOV #0x40, W7`

Step 10: Set NVMCON to erase 1 row of executive memory.		
0000 0000	24071A 883B0A	`MOV #0x4071, W10` `MOV W10, NVMCON`
Step 11: Unlock the NVMCON to erase 1 row of executive memory.		

0000
0000
0000
0000
	200558
	883B38
	200AA9
	883B39
		`MOV #0x55, W8`
		`MOV W8, NVMKEY`
		`MOV #0xAA, W9`
		`MOV W9, NVMKEY`

Step 12: Initiate the erase cycle.		

0000
0000
0000
—
 	
0000
0000
0000
0000
0000
	A8E761
	000000
	000000
	—
	
	000000
	000000
	A9E761
	000000
	000000
		`BSET NVMCON, #WR`
		`NOP`
		`NOP`
		`Externally time 'P13a' ms` (see **Section 13.0 "AC/DC Characteristics and Timing Requirements"**)
		`NOP`
		`NOP`
		`BCLR NVMCON, #WR`
		`NOP`
		`NOP`

Step 13: Update the row address stored in NVMADR.		
0000 0000	430307 883B16	`ADD W6, W7, W6` `MOV W6, NVMADR`
Step 14: Reset device internal PC.		
0000 0000	040100 000000	`GOTO 0x100` `NOP`
Step 15: Repeat Steps 10-14 until all 24 rows of executive memory are erased.		
Step 16: Initialize NVMADR and NVMADRU to erase data memory and initialize W7 for row address updates.		

0000
0000
0000
0000
0000
	2XXXX6
	883B16
	2007F6
	883B16
	200207
		`MOV #<lower 16-bits of starting Data EEPROM address>, W6`
		`MOV W6, NVMADR`
		`MOV #0x7F, W6`
		`MOV W6, NVMADRU`
		`MOV #0x20, W7`

Step 17: Set NVMCON to erase 1 row of data memory.		
0000 0000	24075A 883B0A	`MOV #0x4075, W10` `MOV W10, NVMCON`

TABLE 11-5: SERIAL INSTRUCTION EXECUTION FOR ERASING PROGRAM MEMORY (EITHER IN LOW-VOLTAGE OR NORMAL-VOLTAGE SYSTEMS) (CONTINUED)

Command (Binary)	Data (Hexadecimal)	Description
Step 18: Unlock the NVMCON to erase 1 row of data memory.		
0000	200558	`MOV #0x55, W8`
0000	883B38	`MOV W8, NVMKEY`
0000	200AA9	`MOV #0xAA, W9`
0000	883B39	`MOV W9, NVMKEY`
Step 19: Initiate the erase cycle.		
0000	A8E761	`BSET NVMCON, #WR`
0000	000000	`NOP`
0000	000000	`NOP`
—	—	`Externally time 'P13a' ms` (see **Section 13.0 "AC/DC Characteristics and Timing Requirements"**)
0000	000000	`NOP`
0000	000000	`NOP`
0000	A9E761	`BCLR NVMCON, #WR`
0000	000000	`NOP`
0000	000000	`NOP`
Step 20: Update the row address stored in NVMADR.		
0000	430307	`ADD W6, W7, W6`
0000	883B16	`MOV W6, NVMADR`
Step 21: Reset device internal PC.		
0000	040100	`GOTO 0x100`
0000	000000	`NOP`
Step 22: Repeat Steps 17-21 until all rows of data memory are erased.		

TABLE 11-7: SERIAL INSTRUCTION EXECUTION FOR WRITING CONFIGURATION REGISTERS (CONTINUED)

Command (Binary)	Data (Hexadecimal)	Description
Step 6: Write the Configuration register data to the write latch and increment the write pointer.		

0000
0000
0000
	BB1B96
	000000
	000000
		`TBLWTL W6, [W7++]`
		`NOP`
		`NOP`

Step 7: Unlock the NVMCON for programming.		

0000
0000
0000
0000
	200558
	883B38
	200AA9
	883B39
		`MOV #0x55, W8`
		`MOV W8, NVMKEY`
		`MOV #0xAA, W9`
		`MOV W9, NVMKEY`

Step 8: Initiate the write cycle.		

0000
0000
0000
—
 	
0000
0000
0000
0000
0000
	A8E761
	000000
	000000
	—
	
	000000
	000000
	A9E761
	000000
	000000
		`BSET NVMCON, #WR`
		`NOP`
		`NOP`
		`Externally time 'P12a' ms` (see **Section 13.0 "AC/DC Characteristics and Timing Requirements"**)
		`NOP`
		`NOP`
		`BCLR NVMCON, #WR`
		`NOP`
		`NOP`

Step 9: Reset device internal PC.		
0000 0000	040100 000000	`GOTO 0x100` `NOP`
Step 10: Repeat steps 3-9 until all 7 Configuration registers are cleared.		

11.8 Writing Code Memory

The procedure for writing code memory is similar to the procedure for clearing the Configuration registers, except that 32 instruction words are programmed at a time. To facilitate this operation, working registers W0:W5 are used as temporary holding registers for the data to be programmed.

Table 11-8 shows the ICSP programming details, including the serial pattern with the ICSP command code, which must be transmitted Least Significant bit first using the PGC and PGD pins (see Figure 11-2). In Step 1, the Reset vector is exited. In Step 2, the NVMCON register is initialized for single-panel programming of code memory. In Step 3, the 24-bit starting destination address for programming is loaded into the TBLPAG register and W7 register. The upper byte of the starting destination address is stored to TBLPAG, while the lower 16 bits of the destination address are stored to W7.

To minimize the programming time, the same packed instruction format that the programming executive uses is utilized (Figure 8-2). In Step 4, four packed instruction words are stored to working registers W0:W5 using the `MOV` instruction and the read pointer W6 is initialized. The contents of W0:W5 holding the packed instruction word data is shown in Figure 11-4.

In Step 5, eight `TBLWT` instructions are used to copy the data from W0:W5 to the write latches of code memory. Since code memory is programmed 32 instruction words at a time, Steps 4 and 5 are repeated eight times to load all the write latches (Step 6).

After the write latches are loaded, programming is initiated by writing to the NVMKEY and NVMCON registers in Steps 7 and 8. In Step 9, the internal PC is reset to 0x100. This is a precautionary measure to prevent the PC from incrementing into unimplemented memory when large devices are being programmed. Lastly, in Step 10, Steps 2-9 are repeated until all of code memory is programmed.

FIGURE 11-5: PACKED INSTRUCTION WORDS IN W0:W5

	15 … 8	7 … 0
W0	lsw0	
W1	MSB1	MSB0
W2	lsw1	
W3	lsw2	
W4	MSB3	MSB2
W5	lsw3	

TABLE 11-8: SERIAL INSTRUCTION EXECUTION FOR WRITING CODE MEMORY

Command (Binary)	Data (Hexadecimal)	Description
Step 1: Exit the Reset vector.		

0000
0000
0000
	040100
	040100
	000000
		`GOTO 0x100`
		`GOTO 0x100`
		`NOP`

Step 2: Set the NVMCON to program 32 instruction words.		
0000 0000	24001A 883B0A	`MOV #0x4001, W10` `MOV W10, NVMCON`
Step 3: Initialize the write pointer (W7) for `TBLWT` instruction.		

0000
0000
0000
	200xx0
	880190
	2xxxx7
		MOV #<DestinationAddress23:16>, W0
		MOV W0, TBLPAG
		MOV #<DestinationAddress15:0>, W7

Step 4: Initialize the read pointer (W6) and load W0:W5 with the next 4 instruction words to program.		

0000
0000
0000
0000
0000
0000
	2xxxx0
	2xxxx1
	2xxxx2
	2xxxx3
	2xxxx4
	2xxxx5
		MOV #<LSW0>, W0
		MOV #<MSB1:MSB0>, W1
		MOV #<LSW1>, W2
		MOV #<LSW2>, W3
		MOV #<MSB3:MSB2>, W4
		MOV #<LSW3>, W5

TABLE 11-10: SERIAL INSTRUCTION EXECUTION FOR READING CODE MEMORY (CONTINUED)

Command (Binary)	Data (Hexadecimal)	Description
Step 4: Output W0:W5 using the VISI register and REGOUT command.		
0000	883C20	MOV W0, VISI
0000	000000	NOP
0001	<VISI>	Clock out contents of VISI register
0000	000000	NOP
0000	883C21	MOV W1, VISI
0000	000000	NOP
0001	<VISI>	Clock out contents of VISI register
0000	000000	NOP
0000	883C22	MOV W2, VISI
0000	000000	NOP
0001	<VISI>	Clock out contents of VISI register
0000	000000	NOP
0000	883C23	MOV W3, VISI
0000	000000	NOP
0001	<VISI>	Clock out contents of VISI register
0000	000000	NOP
0000	883C24	MOV W4, VISI
0000	000000	NOP
0001	<VISI>	Clock out contents of VISI register
0000	000000	NOP
0000	883C25	MOV W5, VISI
0000	000000	NOP
0001	<VISI>	Clock out contents of VISI register
0000	000000	NOP
Step 5: Reset the device internal PC.		
0000	040100	GOTO 0x100
0000	000000	NOP
Step 6: Repeat steps 3-5 until all desired code memory is read.		

13.0 AC/DC CHARACTERISTICS AND TIMING REQUIREMENTS

TABLE 13-1: AC/DC CHARACTERISTICS

AC/DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating Temperature: 25° C is recommended			
Param. No.	**Sym**	**Characteristic**	**Min**	**Max**	**Units**	**Conditions**
D110	VIHH	High Programming Voltage on $\overline{\text{MCLR}}$/VPP	9.00	13.25	V	—
D112	IPP	Programming Current on $\overline{\text{MCLR}}$/VPP	—	300	μA	—
D113	IDDP	Supply Current during programming	—	30	mA	Row Erase Program memory
			—	30	mA	Row Erase Data EEPROM
			—	30	mA	Bulk Erase
D001	VDD	Supply voltage	2.5	5.5	V	—
D002	VDDBULK	Supply voltage for Bulk Erase programming	4.5	5.5	V	—
D031	VIL	Input Low Voltage	VSS	0.2 VSS	V	—
D041	VIH	Input High Voltage	0.8 VDD	VDD	V	—
D080	VOL	Output Low Voltage	—	0.6	V	IOL = 8.5 mA
D090	VOH	Output High Voltage	VDD - 0.7	—	V	IOH = -3.0 mA
D012	CIO	Capacitive Loading on I/O Pin (PGD)	—	50	pF	To meet AC specifications
P1	TSCLK	Serial Clock (PGC) period	50	—	ns	ICSP™ mode
			1	—	μs	Enhanced ICSP mode
P1a	TSCLKL	Serial Clock (PGC) low time	20	—	ns	ICSP mode
			400	—	ns	Enhanced ICSP mode
P1b	TSCLKH	Serial Clock (PGC) high time	20	—	ns	ICSP mode
			400	—	ns	Enhanced ICSP mode
P2	TSET1	Input Data Setup Timer to PGC ↓	15	—	ns	—
P3	THLD1	Input Data Hold Time from PGC ↓	15	—	ns	—
P4	TDLY1	Delay between 4-bit command and command operand	20	—	ns	—
P4a	TDLY1a	Delay between 4-bit command operand and next 4-bit command	20	—	ns	—
P5	TDLY2	Delay between last PGC ↓of command to first PGC ↑ of VISI output	20	—	ns	—
P6	TSET2	VDD ↑ setup time to $\overline{\text{MCLR}}$/VPP	100	—	ns	—
P7	THLD2	Input data hold time from $\overline{\text{MCLR}}$/VPP ↑	2	—	μs	ICSP mode
			5	—	ms	Enhanced ICSP mode
P8	TDLY3	Delay between last PGC ↓of command word to PGD driven ↑ by programming executive	20	—	μs	—
P9a	TDLY4	Programming Executive Command processing time	10	—	μs	—

APPENDIX A: DEVICE-SPECIFIC INFORMATION

A.1 Checksum Computation

The checksum computation is described in **Section 6.8 "Checksum Computation"**. Table A-1 shows how this 16-bit computation can be made for each dsPIC30F device. Computations for read code protection are shown both enabled and disabled. The checksum values assume that the Configuration registers are also erased. However, when code protection is enabled, the value of the FGS register is assumed to be 0x5.

A.2 dsPIC30F5011 and dsPIC30F5013

A.2.1 ICSP PROGRAMMING

The dsPIC30F5011 and dsPIC30F5013 processors require that the FBS and FSS registers be programmed with 0x0000 before the device is chip erased. The steps to perform this action are shown in Table 11-4.

A.2.2 ENHANCED ICSP PROGRAMMING

The dsPIC30F5011 and dsPIC30F5013 processors require that the FBS and FSS registers be programmed with 0x0000 using the `PROGC` command before the `ERASEB` command is used to erase the chip.

TABLE A-1: CHECKSUM COMPUTATION

Device	Read Code Protection	Checksum Computation	Erased Value	Value with 0xAAAAAA at 0x0 and Last Code Address
dsPIC30F2010	Disabled	CFGB+SUM(0:001FFF)	0xD406	0xD208
	Enabled	CFGB	0x0404	0x0404
dsPIC30F2011	Disabled	CFGB+SUM(0:001FFF)	0xD406	0xD208
	Enabled	CFGB	0x0404	0x0404
dsPIC30F2012	Disabled	CFGB+SUM(0:001FFF)	0xD406	0xD208
	Enabled	CFGB	0x0404	0x0404
dsPIC30F3010	Disabled	CFGB+SUM(0:003FFF)	0xA406	0xA208
	Enabled	CFGB	0x0404	0x0404
dsPIC30F3011	Disabled	CFGB+SUM(0:003FFF)	0xA406	0xA208
	Enabled	CFGB	0x0404	0x0404
dsPIC30F3012	Disabled	CFGB+SUM(0:003FFF)	0xA406	0xA208
	Enabled	CFGB	0x0404	0x0404
dsPIC30F3013	Disabled	CFGB+SUM(0:003FFF)	0xA406	0xA208
	Enabled	CFGB	0x0404	0x0404
dsPIC30F3014	Disabled	CFGB+SUM(0:003FFF)	0xA406	0xA208
	Enabled	CFGB	0x0404	0x0404
dsPIC30F4011	Disabled	CFGB+SUM(0:007FFF)	0x4406	0x4208
	Enabled	CFGB	0x0404	0x0404
dsPIC30F4012	Disabled	CFGB+SUM(0:007FFF)	0x4406	0x4208
	Enabled	CFGB	0x0404	0x0404
dsPIC30F4013	Disabled	CFGB+SUM(0:007FFF)	0x4406	0x4208
	Enabled	CFGB	0x0404	0x0404
dsPIC30F5011	Disabled	CFGB+SUM(0:00AFFF)	0xFC06	0xFA08
	Enabled	CFGB	0x0404	0x0404
dsPIC30F5013	Disabled	CFGB+SUM(0:00AFFF)	0xFC06	0xFA08
	Enabled	CFGB	0x0404	0x0404
dsPIC30F5015	Disabled	CFGB+SUM(0:00AFFF)	0xFC06	0xFA08
	Enabled	CFGB	0x0404	0x0404

Item Description:

SUM(a:b) = Byte sum of locations a to b inclusive (all 3 bytes of code memory)

CFGB = **Configuration Block (masked)** = Byte sum of ((FOSC&0xC10F) + (FWDT&0x803F) + (FBORPOR&0x87B3) + (FBS&0x310F) + (FSS&0x330F) + (FGS&0x0007) + (FICD&0xC003))

APPENDIX C: REVISION HISTORY

Note:	Revision histories were not recorded for revisions A through H. The previous revision (J), was published in August 2007.

Revision K (November 2010)

This version of the document includes the following updates:

- Added Note three to **Section 5.2 "Entering Enhanced ICSP Mode"**
- Updated the first paragraph of **Section 10.0 "Device ID"**
- Updated Table 10-1: Device IDs
- Removed the VARIANT bit and updated the bit definition for the DEVID register in Table 10-2: dsPIC30F Device ID Registers
- Removed the VARIANT bit and updated the bit field definition and description for the DEVID register in Table 10-3: Device ID Bits Description
- Updated Note 3 in **Section 11.3 "Entering ICSP Mode"**
- Updated Step 11 in Table 11-4: Serial Instruction Execution for BUlk Erasing Program Memory (Only in Normal-voltage Systems)
- Updated Steps 5, 12 and 19 in Table 11-5: Serial Instruction Execution for Erasing Program Memory (Either in Low-voltage or Normal-voltage Systems)
- Updated Steps 5, 6 and 8 in Table 11-7: Serial Instruction Execution for Writing Configuration Registers
- Updated Steps 6 and 8 in Table 11-8: Serial Instruction Execution for Writing Code Memory
- Updated Steps 6 and 8 in Table 11-9: Serial Instruction Execution for Writing Data EEPROM
- Updated Entering ICSP™ Mode (see Figure 11-4)
- Updated Steps 4 and 11 in Table 12-1: Programming the Programming Executive
- Renamed parameters: P12 to P12a and P13 to P13a, and added parameters P12b and P13b in Table 13-1: AC/DC Characteristics

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